

无铅锡丝 Sn65Ag25Sb10

Lead-free Solder Wire Sn65Ag25Sb10

技术数据表 Technical Data Sheet

1.适用范围 APPLICATION

本产品适用于电子产品中各组件之间的焊接封装制程。

This product is suitable for welding and packaging process between components of electronic products.

2.产品信息 PRODUCT INFORMATION

名称 Name	主要组元 Component		熔点 Melting Point	比重 Specific Gravity
无铅锡丝 Sn65Ag25Sb10	Sn	65%	233℃	7.8g/cm ³
Lead-free Solder Wire	Ag	25%		
Sn65Ag25Sb10	Sb	10%		

3.化学成分 CHEMICAL COMPOSITION

项次 Item	规格 Specification									
	组元 Component(%)			不纯物 Impurity(%)						
Solder	Sn	Ag	Sb	Cu	Bi	Pb	Fe	As	Cd	Al
焊锡	65±0.5	25±0.5	10±0.5	<0.08	<0.1	<0.1	<0.02	<0.03	<0.002	<0.001

4.品质 QUALITY

4.1 外观 APPEARANCE

锡丝表面应光滑、清洁，不应存在裂纹、夹杂、油污等。

Surface of solder wire should be smooth and clean; there also should be no cracks, inclusions, oil and so on.

4.2 尺寸公差 DIMENSIONAL TOLERANCES

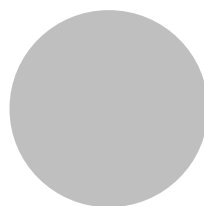


图 1 锡丝截面示意图

FIG.1 SKETCH MAP

直径 (毫米) Dimension (mm)	公差 (毫米) (Tolerance) (mm)
≤ 0.3	± 0.02
0.3-0.8	± 0.03
$> 0.8-2.5$	± 0.05
$> 2.5-6.0$	± 0.10

5.包装 PACKAGING

5.1 标签 MARKING

标签应包含以下信息: Mark should include the following information:

制造商名称或商标 Manufacturer's name or trademark

生产日期 Production date

产品名称 Product name

保固期限 Validity

5.2 线卷轮信息 ROLL INFORMATION (参考)

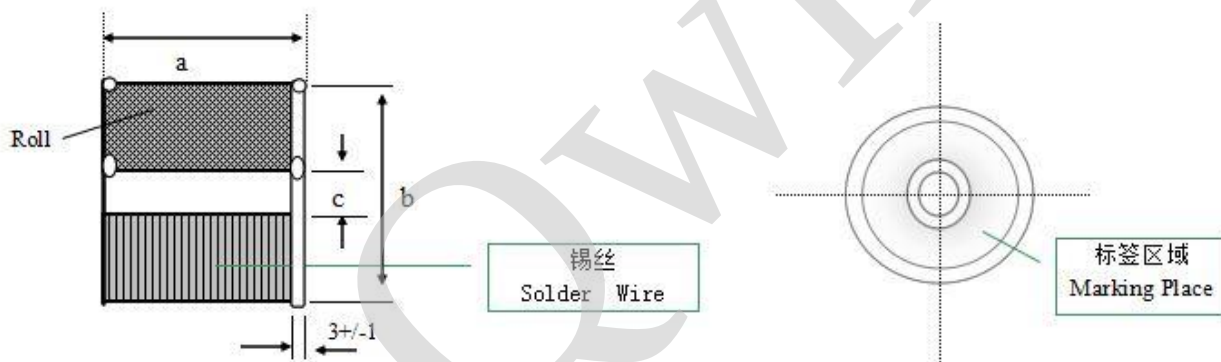


图 2 线卷轮示意图

FIG.2 SKETCH MAP

Net Weight/ Roll 净重/卷	Dimension 尺寸		
	a	b	c
200g	72mm	68mm	20mm

5.3 包装 PACKAGING

通常每卷 200G, 每 10 卷为一箱, 箱身贴有标签。

Usually 200G per roll, each 10 rolls in a box with attached labels.

不同材质、直径、松香含量有所不同, 具体以实际包装为准。

Different materials, diameter, rosin content are different, so actual package shall prevail.

6. 储存条件与期限 STORAGE

本产品在室内常温（温度： $20 \pm 10^{\circ}\text{C}$ ，湿度： $<55\%\text{RH}$ ）下储存期限为 2 年。

This product can be stored for 2 years under indoor normal temperature (temperature: $20 \pm 10^{\circ}\text{C}$, humidity: $<55\%\text{RH}$).

Qwin